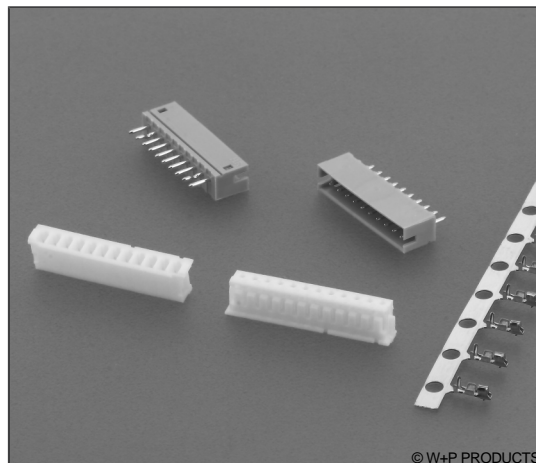


Crimp-Rast-Stift-/Buchsenleisten RM 1,50mm, gerade, 1-reihig Friction Lock Headers / Crimp Housings, 1.50mm Pitch, Straight, Single Row

Technische Daten / Technical Data

Isolierkörper	Thermoplastischer Kunststoff, nach UL94 V-0
Insulator	Thermoplastic, rated UL94 V-0
Kontaktmaterial	Rundstift 0,50mm, Kupferlegierung
Contact Material	Round pin 0.50mm, Copper alloy
Aderquerschnitt	AWG 32 ~ 28
Applicable wire Gauge	AWG 32 ~ 28
Durchgangswiderstand	< 20mΩ
Contact Resistance	< 20mΩ
Isolationswiderstand	> 500MΩ
Insulation Resistance	> 500MΩ
Spannungsfestigkeit	500V _{AC}
Test Voltage	500V _{AC}
Nennspannung	100V _{AC}
Voltage Rating	100V _{AC}
Nennstrom	1A
Current Rating	1A
Temperaturbereich	-25°C ... +85°C
Temperature Range	-25°C ... +85°C
Verarbeitung	Wellenlötverfahren
Processing	Wave soldering

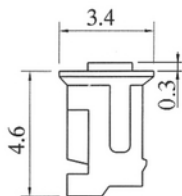
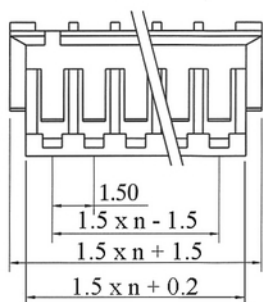


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Passende SMT-Stiftleisten:
Compatible SMT Pin Headers:

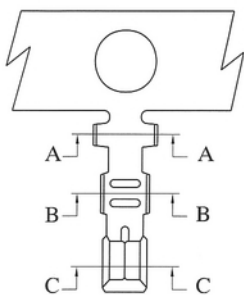
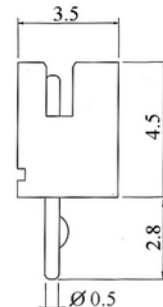
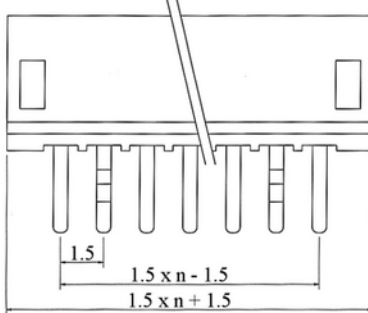
5690

Housing

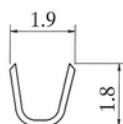
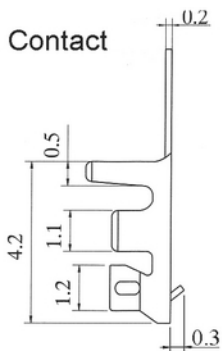


n = Anzahl Kontakte
n = No. of Contacts

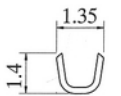
Header



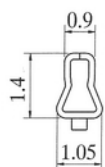
Contact



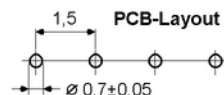
SEC A-A



SEC B-B



SEC C-C



Series

569

Contacts*

08

02-13
01 (für Buchsenkontakte)
(for crimp contacts)

Type*

3

1 Buchsengehäuse
Housing
2 Buchsenkontakte
Crimp contacts
3 Stiftleiste gerade
Straight pin header

Plating

50

50 Verzinkt (bei Gehäusen nicht erforderlich)
Tin plated (not necessary for housings)

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** -
please replace by your specifications.

Empfehlungen für das Wellenlötverfahren

Recommendations for Wave Soldering

Die Bauteile sollten bei einer Lötbadtemperatur von 260°C in max. 5 Sekunden verlötet werden.
Items should be soldered at a solder temperature of 260°C in 5 seconds max.

Empfohlenes Wellenlötprofil:
Recommended wave soldering profile:

